Future (heterogeneous) system integration especially when fast switching SiC or GaN power devices are involved:

- alleviate problems related to fast switching on the module or SIP level

- reduce number of production steps (cost savings)

- high production volume required to justify initial costs

- select the partitioning and interfaces intelligently!

Which partitioning makes sense:

Switching Cell in Package
- this critical part of the circuit is encapsulated in the package

Power System in Package
- integration of full functions including passives
- Examples: PFC, DC/DC converter, half bridge including output inductor

ECPE Lighthouse Programme:

msPEBB   : modular and scalable Power Electronics Building Block